KMY

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Specification

(Reference)

Title: CHIP FUSE; RECTANGULAR TYPE

Style: FMC10, 16

RoHS COMPLIANCE ITEM Halogen and Antimony Free

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Issue Dept.: Research & Development Department Hokkaido Research Center

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1. Scope

1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of FMC10, 16.

1.2 Applicable documents

UL248–1–2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

2. Classification

Type designation shall be the following form.

4 Optional code

Symbol	Optional code			
AB				
WB	Standard			
WH				

5 Packaging form

3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1-00 and CSA C22.2, No. 248.14-00

The file number to be designated by UL and C-UL shall be as follows: E176847

4. Rating

The ratings shall be in accordance with Table-1.

4.1 Optional code: AB

Table-1(1)

	Iable–1(1)							
	F	Rated curre	ent	Internal resistance value	Rated	Breaking	Time / cur	rent characteristic
Style	Symbol	(A)	Marking symbol	(m Ω max.)	voltage (V)	capacity (A)	Time / cur Current 100% 200% 300%	Pre-arcing time
	501							
	751	0.75	Α	140			200%	4 h min. 5 s max. 0.2 s max.
	102	1.0	L	95				
FMC10	132	1.25	М	73	DC24	35		
TIVICTO	152	1.5	Н	60	DC24	33		
	202	2.0	S	41				
	252	2.5	Т	32				
	302	3.0	R	25				

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4.2 Optional code: WB

Table-1(2)

	F	Rated curre	ent	Internal resistance value	Rated	Breaking	Time / cur	rent characteristic
Style	Symbol	(A)	Marking symbol	(m Ω max.)	voltage (V)	capacity (A)	Time / cu Current 100% 200% 300%	Pre-arcing time
	501	0.5	F	260				
	751	0.75	Α	140				
	102	1.0	L	110			4000/	4 h min. 5 s max. 0.2 s max.
	132	1.25	М	80				
FMC16	152	1.5	Н	65	DC32	35		
FIVIC 16	202	2.0	S	45	DC32	33		
	252	2.5	Т	32]		30076	
	302	3.0	R	26				
	402	4.0	Χ	18				
	502	5.0	Υ	14				

4.3 Optional code: WH

Table-1(3)

				1able-1(3)				
	F	Rated curre	ent	Internal resistance value	Rated	Breaking	Time / curr	ent characteristic
Style	Symbol	(A)	Marking symbol	$(m\Omega \max.)$	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	<u>F</u>	250				
	751	0.75	<u>A</u>	250 150 100 70 60 40 25 25 24 18 14				
	102	1.0	LI	100				
	132	1.25	<u>M</u>	70				
	152	1.5	<u>H</u>	60			100%	4 h min.
FMC10	202	2.0	<u>S</u>	40	DC24	35		5 s max.
	252	2.5	Ţ	30			300%	0.2 s max.
	302	3.0	<u>R</u>	25				
	322	3.15	<u>U</u>	24				
	402	4.0	<u>X</u>	18				
	502	5.0	<u>Y</u>	14				
	501	0.5	OF	400				
	631	0.63	O	300				
	751	0.75	OA	210				
	801	0.8	OK	180				
	102	1.0	OL	115				
	132	1.25	OM	90			100%	4 h min.
FMC16	152	1.5	OH	70	DC32	35	200%	5 s max.
1 IVIC 10	162	1.6	ON	60	DC3Z		300%	0.2 s max.
	202	2.0	OS	50			30070	0.2 3 max.
	252	2.5	OT	37				
	302	3.0	OR	28				
	322	3.15	OU	26				
	402	4.0	OX	18				
	502	5.0	OY	14				

4.4 Working temperature range: -55 to +125(°C)

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5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	FMC10, 16
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	FMC10
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	FMC16

6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

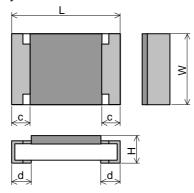


Figure-1

Table-3	Unit: mm
14015-0	CHILL HILL

Style	Optional code	L	W	Н	С	d
EMC10	WH	101005	0.5±0.05	0.35±0.05	0.2±0.10	0.25±0.10
FMC10	AB	1.0±0.05		0.38±0.05		
FMC16	WB,WH	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.15	0.3±0.1

6.2 Net weight (Reference)

Style	Net weight(mg)
FMC10	0.6
FMC16	2

7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

(Example)

ν-	2/41/1919)						
	Style	Optional code	Marking symbol	Content			
	FMC10	AB	S	FMC10 202 AB			
	FMC10	WH	<u>S</u>	FMC10 202 WH			
	FMC16	WB	S	FMC16 202 WB			
	FMC16	WH	OS	FMC16 202 WH			



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8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C \pm 2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

8.2 The performance shall be satisfied in Table-4.

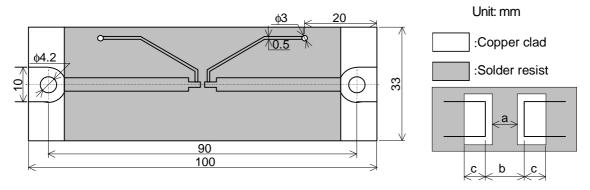
Table-4(1)

No.	Test items	Condition of test	Perforr	mance requirements
1	Temperature rise	The fuse shall be mounted on the test substrate as shown in Figure–2. Measurement temp.: 10 °C to 30 °C Test current: Rated current The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained.	75 °C max	
2	Time / current characteristic	The fuse shall be mounted on the test substrate as shown in Figure–2. Test current shall be applied for continuously.	Current 100% 200% 300%	Pre–arcing time 4 h min. 5 s. max. 0.2 s max.
3	Terminal bond strength of the face plating	JIS C 60068-2-21 Ue1 The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: 3 mm(Among the fulcrums: 90 mm) Duration: 10 s ± 1 s	Change of ±10% No evide damage.	internal resistance: ence of mechanical
4	Resistance to soldering heat	Test by a piece. Temp. of solder bath: 260 °C ± 5 °C Immersion time: 10 s ± 1 s After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance. • Reflow soldering Pre–heating: 150 °C ~ 180 °C, 120 s max. Peak: 260 °C ± 5 °C, 10 s max. Reflow cycle: 2 times After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.	Change of internal resistance: ±10% No evidence of appearance damage	
5	Solderability	JIS C 60068-2-58 Test by a piece Flux: Rosin–Methanol Temp. of solder: bath: 235 °C ± 5 °C Immersion time: 2 s ± 0.5 s	shall be mi	te of terminal immersed in. of 95 % covered with ing of solder.
6	Rapid change temperature	JIS C 60068-2-14 Na The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles	Change of ±10% No evide damage	internal resistance: ence of appearance

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9. Test substrate



Style	а	b	С
FMC10	0.3	0.6	0.65
FMC16	0.6	1.0	0.5

Figure-2 FMC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

10. Taping

10.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7200B: 2003

10.2 Taping dimensions

10.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.

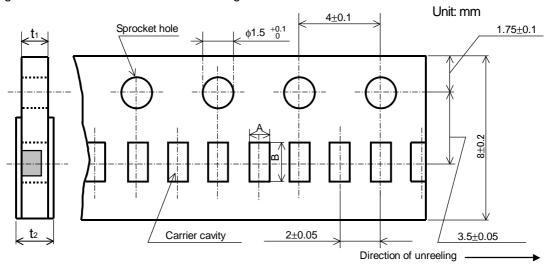


Figure-3

	Unit: mm			
Style	Α	В	t 1	t ₂
FMC10	0.65 +0.05	1.15 ^{+0.05} _{-0.10}	0.4 ± 0.05	0.5max.

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10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.

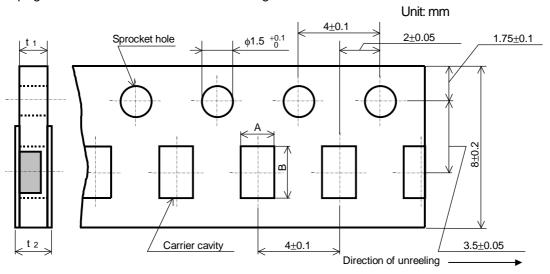


Figure-4
Table-6 Unit: mm

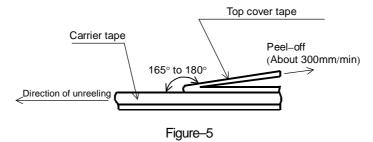
Style A B t₁ t₂

FMC16 1.15±0.15 1.9±0.2 0.6±0.1 0.8 max.

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure-5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



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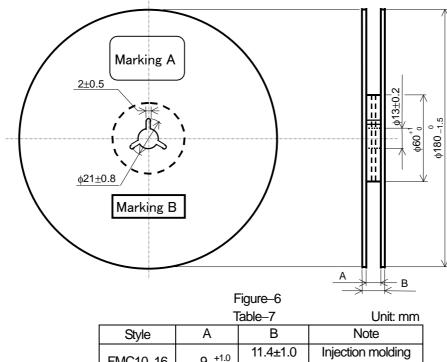
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10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-6 and Table-7.

Plastic reel (Based on EIAJ ET-7200B) Unit: mm



	Table–7		Unit: mm
Style	Α	В	Note
FMC10, 16	9 +1.0	11.4±1.0	Injection molding
		13±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

10.4 Leader and trailer tape.

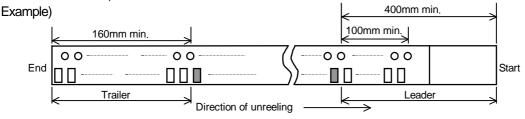


Figure-7

11. Marking on package

The label of a minimum package shall be legibly marked with follows.

11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C-UL recognized component mark

11.2 Marking B (KAMAYA Control label)



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12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

Nominal Derating

Nominal Derating ≤ 75% of Rated Current

*FMC10 Optional code: WH, Rated current ≥ 3.15A: Nominal Derating ≤ 70% of Rated Current

Temperature Derating

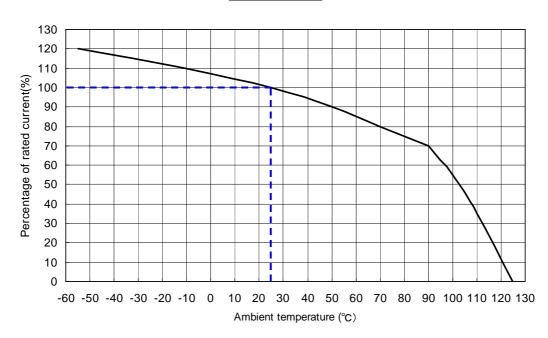
Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If FMC16 202WH (Rated Current 2.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current: 2.0A× (Nominal Derating: 75% × Temperature Derating: 80%) = 1.2A

Derating curve



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